

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MAN-SHU CHIANG	07/01/2019
CHIH-WEI HSU	07/01/2019
RECEIVING PARTY DATA	
Name:	MEDIATEK INC.
Street Address:	NO. 1, DUSING ROAD 1
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU CITY
State/Country:	TAIWAN
Postal Code:	30078
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16513835
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	MDTK.0392US
NAME OF SUBMITTER:	ANDY M. HAN
SIGNATURE:	/Andy M. Han/
DATE SIGNED:	07/23/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3	
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source=MDTK_0392US_Combined_Declaration_Assignment#page2.tif	

**COMBINED DECLARATION AND ASSIGNMENT FOR APPLICATION FOR UNITED STATES
LETTERS PATENT
DECLARATION**

Title of Invention: ***MERGE CANDIDATES WITH MULTIPLE HYPOTHESIS***

As the below named inventor, I hereby declare that:

This declaration is directed to: **(X)** The attached application, or
 () U.S. Application or PCT international application number _____
 filed on _____.

- The above-identified application was made or authorized to be made by me.
- I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
- I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.
- I have reviewed and understand the contents of the present application, including the claims, as amended by any amendment specifically referred to herein.
- I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

I hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below.

U.S. PROVISIONAL APPLICATION NUMBER	DATE OF FILING (MONTH/DAY/ YEAR)
62/699,760	07/18/2018 (18 July 2018)

POWER OF ATTORNEY

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) associated with Customer No.

13859

to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Send Correspondence to:

Han IP PLLC
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Seattle, WA 98101
Direct Telephone Calls To: (949) 383-5385
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ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

1. Man-Shu Chiang
2. Chih-Wei Hsu

Assignee:

MediaTek Inc.

No. 1, Dusing Road 1, Science-Based Industrial Park
Hsinchu City 30078, Taiwan, R.O.C.

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of the above-identified invention for which:

☒ provisional application(s) for United States Letters Patents was/were filed on

18 July 2018 and was/were given U.S. Serial No(s). **62/699,760**; and/or

☒ a non-provisional application for United States Letters Patent was/is:

☐ filed on _____ and was given U.S. Serial No. _____; or filed concurrently herewith.

Assignors hereby authorize and request ASSIGNEE's legal representatives, who are associated with customer number **13859**, to handle all matters related to the above-identified application.

WHEREAS, MediaTek Inc. (hereinafter referred to as ASSIGNEE), a corporation of Taiwan, Republic of China (R.O.C.) having a place of business at No. 1, Dusing Road 1, Science-Based Industrial Park, Hsinchu City 30078, Taiwan, R.O.C., is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

Legal Name of First-Named Inventor: **Man-Shu CHIANG**

Inventor's Signature:

Man-Shu Chiang

Date:

2019.07.01

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Legal Name of Co-Inventor: **Chih-Wei HSU**

Inventor's Signature:

Chih-Wei Hsu

Date:

2019.07.01

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